

**Announcement and Call for Abstracts**  
**Topical Workshop on**  
**Flip Chip, Wafer Level Packaging & Fan-Out**  
*This workshop is being held as a part of the Device Packaging Conference*  
**WeKoPa Resort & Casino**  
**Fountain Hills, Arizona - USA**  
**March 4 - 7, 2019**

Technical Chair:	Technical Co-Chair:	Technical Co-Chair:
<b>Eric Huenger</b> , DOW <a href="mailto:ehuenger@dow.com">ehuenger@dow.com</a>	<b>Curtis Zwenger</b> , Amkor Technology <a href="mailto:Curtis.zwenger@amkor.com">Curtis.zwenger@amkor.com</a>	<b>Nokibul Islam</b> , JCET Group <a href="mailto:Nokibul.islam@statschippac.com">Nokibul.islam@statschippac.com</a>

**Flip Chip, Wafer Level Packaging & Fan-Out Organizing Committee:**

Linda Bal, TechSearch  
 Jae Kyu Cho, GLOBAL  
 FOUNDRIES  
 Scott Hayes, NXP

Amy Lujan, SavanSys  
 Kevin Martin, Atotech USA  
 Chris Scanlan, Deca  
 Rebecca Schmidt, DOW

**Flip Chip, Wafer Level Packaging & Fan-Out Workshop Focus:**

The objective of the Flip Chip, Wafer Level Packaging, and Fan-Out Wafer Level Packaging Technology Workshop is to have a unique forum that brings together scientists, engineers, and business professionals from commercial and R&D sectors around the world to discuss the most recent developments in FC, WLP and FOWLP technologies. This workshop has been specifically organized to allow for the presentation and debate of all aspects of these technologies in an environment that encourages interaction and discussion among the participants.

**Abstracts are being requested on the following topics:**

- **Wafer Level Packaging/Bumping Technology including:**
  - Bumping: Cu Pillar, Pb-Free, micro bumps & fine pitch
  - Redistribution and repassivation
  - Underbump metalizations
  - Fine Pitch <=(0.3mm pitch) WLP technology
  - Enhanced materials and technologies
  - Wafer thinning/Ultra thin
  - Backside coatings & sidewall reinforcements
  - Laser marking
  - Dicing (wafer saw, laser grooving, stealth, plasma)
- **Fan Out Packaging Technology**
  - Fan-out CSP /Re-Constituted Wafer Processing
  - Chip First Fan Out structures & processes
  - Chip Last Fan Out structures and processes
  - Panel Fan Out
- **Flip Chip Packaging Technology**
  - Die Attach (Mass Reflow, Thermal Compression Bonding, etc.)
  - Die to wafer flip chip bonding
  - Substrates, Lids, and Lid Attach
  - Capillary & molded underfill, Non Conductive Paste/film
  - Thermal Interface & Conductive Adhesives
  - Sphere attach and fluxless assembly processes
  - Non-solder based flip chip assembly
- **Design for WLP, Fan Out and Flip chip advancements in:**
  - Substrates and board technologies
  - Substrate design, Layout and Simulation Tools
  - Thermo-mechanical & electrical Modeling
  - Die-Package Co-design
- **Board and Component Level reliability including**  
*electromigration, temperature cycling, HTS, biased humidity*
- **FC, WLP and FOWLP End Use Applications**

Those wishing to present in the Device Packaging Conference must submit a ~500 word abstract electronically **no later than October 26, 2018**, using the on-line submittal form at: [www.imaps.org/abstracts.htm](http://www.imaps.org/abstracts.htm). No formal technical paper is required. A reproduction-ready two- to four-page "extended abstract" with text (figures and graphs included if necessary) **will be required for the abstract booklet on January 31, 2019**. Please contact Brian Schieman by email at [bschieman@imaps.org](mailto:bschieman@imaps.org) if you have questions. **STUDENT AUTHORS:** upon abstract submission, please select "**yes, I'm a full-time student**" on the form and you will automatically be entered in the student competition with \$3000 in foundation awards (\$1500 1<sup>st</sup>, \$1000 2<sup>nd</sup>, \$500 3<sup>rd</sup>).

**Device Packaging Exhibit and Technology Show:**

IMAPS will hold a concurrent exhibition for vendors and suppliers who support the many aspects of **Flip Chip, Wafer Level Packaging & Fan-Out**. This venue features an ideal atmosphere to showcase your products and services to key decision making professionals in the industry. Full 8' by 10' exhibit spaces will be available. To reserve booth space please fill out the on-line submittal form before December 1, 2018 at: [www.imaps.org/devicepackaging](http://www.imaps.org/devicepackaging) or contact Brian Schieman by email at [bschieman@imaps.org](mailto:bschieman@imaps.org).

**Device Packaging Professional Development Courses (PDCs):**

For those wishing to broaden their knowledge of device packaging, a selection of half-day courses will be offered on Monday, March 4<sup>th</sup>, preceding the technical conference. If you would like to participate as an instructor, please submit a description of your short course on-line at [www.imaps.org/pdc](http://www.imaps.org/pdc) **no later than October 26, 2018**.